

3D IC & 2.5D IC Packaging Market Research Report by Technology (2.5D, 3D TSV, and 3D Wafer-Level Chip-Scale Packaging), by End User (Automotive, Consumer Electronics, Industrial Sector, Medical Devices, and Military & Aerospace), by Application - Global Forecast to 2025 - Cumulative Impact of COVID-19

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Abstracts

Market Statistics:

The report provides market sizing and forecast across five major currencies - USD, EUR GBP, JPY, and AUD. This helps organization leaders make better decisions when currency exchange data is readily available.

1. The Global 3D IC & 2.5D IC Packaging Market is expected to grow from USD 44,323.69 Million in 2020 to USD 146,564.70 Million by the end of 2025.
2. The Global 3D IC & 2.5D IC Packaging Market is expected to grow from EUR 38,863.85 Million in 2020 to EUR 128,510.71 Million by the end of 2025.
3. The Global 3D IC & 2.5D IC Packaging Market is expected to grow from GBP 34,550.05 Million in 2020 to GBP 114,246.30 Million by the end of 2025.
4. The Global 3D IC & 2.5D IC Packaging Market is expected to grow from JPY 4,730,461.23 Million in 2020 to JPY 15,642,168.10 Million by the end of 2025.
5. The Global 3D IC & 2.5D IC Packaging Market is expected to grow from AUD 64,363.89 Million in 2020 to AUD 212,831.44 Million by the end of 2025.

Market Segmentation & Coverage:

This research report categorizes the 3D IC & 2.5D IC Packaging to forecast the revenues and analyze the trends in each of the following sub-markets:

Based on Technology, the 3D IC & 2.5D IC Packaging Market studied across 2.5D, 3D TSV, and 3D Wafer-Level Chip-Scale Packaging.

Based on End User, the 3D IC & 2.5D IC Packaging Market studied across Automotive, Consumer Electronics, Industrial Sector, Medical Devices, Military & Aerospace, Smart Technologies, and Telecommunication.

Based on Application, the 3D IC & 2.5D IC Packaging Market studied across Imaging & Optoelectronics, LED, Logic, MEMS/Sensors, Memory, Photonics, Power, Analog and Mixed Signal, RF, and Photonics, and RF.

Based on Geography, the 3D IC & 2.5D IC Packaging Market studied across Americas, Asia-Pacific, and Europe, Middle East & Africa. The Americas region surveyed across Argentina, Brazil, Canada, Mexico, and United States. The Asia-Pacific region surveyed across Australia, China, India, Indonesia, Japan, Malaysia, Philippines, South Korea, and Thailand. The Europe, Middle East & Africa region surveyed across France, Germany, Italy, Netherlands, Qatar, Russia, Saudi Arabia, South Africa, Spain, United Arab Emirates, and United Kingdom.

Company Usability Profiles:

The report deeply explores the recent significant developments by the leading vendors and innovation profiles in the Global 3D IC & 2.5D IC Packaging Market including 3M Company, Advanced Semiconductor Engineering, Inc., Amkor Technology, Apple Inc, ASE Group, BeSang Inc., Broadcom Ltd, Fujitsu Limited, IBM Corporation, Intel Corporation., Jiangsu Changjiang Electronics Technology Co. Ltd, Monolithic 3D Inc., Pure Storage, Inc., Samsung Electronics Co. Ltd, Siliconware Precision Industries Co., STMicroelectronics NV, Taiwan Semiconductor Manufacturing Company Limited, Texas Instruments Incorporated, Tezzaron Semiconductor Corporation, Toshiba Electronic Devices & Storage Corporation, United Microelectronics Corporation, and Xilinx Inc..

Cumulative Impact of COVID-19:

COVID-19 is an incomparable global public health emergency that has affected almost every industry, so far and, the long-term effects projected to impact the industry growth during the forecast period. Our ongoing research amplifies our research framework to ensure the inclusion of underlying COVID-19 issues and potential paths forward. The report is delivering insights on COVID-19 considering the changes in consumer behavior and demand, purchasing patterns, re-routing of the supply chain, dynamics of current market forces, and the significant interventions of governments. The updated

study provides insights, analysis, estimations, and forecast, considering the COVID-19 impact on the market.

360iResearch FPNV Positioning Matrix:

The 360iResearch FPNV Positioning Matrix evaluates and categorizes the vendors in the 3D IC & 2.5D IC Packaging Market on the basis of Business Strategy (Business Growth, Industry Coverage, Financial Viability, and Channel Support) and Product Satisfaction (Value for Money, Ease of Use, Product Features, and Customer Support) that aids businesses in better decision making and understanding the competitive landscape.

360iResearch Competitive Strategic Window:

The 360iResearch Competitive Strategic Window analyses the competitive landscape in terms of markets, applications, and geographies. The 360iResearch Competitive Strategic Window helps the vendor define an alignment or fit between their capabilities and opportunities for future growth prospects. During a forecast period, it defines the optimal or favorable fit for the vendors to adopt successive merger and acquisition strategies, geography expansion, research & development, and new product introduction strategies to execute further business expansion and growth.

The report provides insights on the following pointers:

1. **Market Penetration:** Provides comprehensive information on the market offered by the key players
2. **Market Development:** Provides in-depth information about lucrative emerging markets and analyzes the markets
3. **Market Diversification:** Provides detailed information about new product launches, untapped geographies, recent developments, and investments
4. **Competitive Assessment & Intelligence:** Provides an exhaustive assessment of market shares, strategies, products, and manufacturing capabilities of the leading players
5. **Product Development & Innovation:** Provides intelligent insights on future technologies, R&D activities, and new product developments

The report answers questions such as:

1. What is the market size and forecast of the Global 3D IC & 2.5D IC Packaging Market?
2. What are the inhibiting factors and impact of COVID-19 shaping the Global 3D IC & 2.5D IC Packaging Market during the forecast period?
3. Which are the products/segments/applications/areas to invest in over the forecast

period in the Global 3D IC & 2.5D IC Packaging Market?

4. What is the competitive strategic window for opportunities in the Global 3D IC & 2.5D IC Packaging Market?

5. What are the technology trends and regulatory frameworks in the Global 3D IC & 2.5D IC Packaging Market?

6. What are the modes and strategic moves considered suitable for entering the Global 3D IC & 2.5D IC Packaging Market?

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